

HALOGEN FREE



N-Channel 40-V (D-S) MOSFET

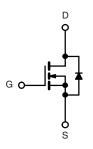
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)	
40	0.0088 at V _{GS} = 10 V	50	16 nC	
40	0.0105 at V _{GS} = 4.5 V	50	10110	

FEATURES

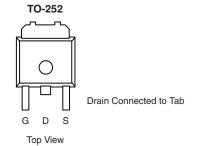
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- 100 % UIS Tested
- 100 % R_q Tested
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- · LCD Display Backlight Inverters
- DC/DC Converters



N-Channel MOSFET



Ordering Information: SUD50N04-8m8P-4GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	40		
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		50 ^a		
Continuous Drain Current (T. 150 °C)	T _C = 70 °C		44		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	14 ^b		
	T _A = 70 °C		11.2 ^b		
Pulsed Drain Current		I _{DM}	100	Α	
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	40		
	T _A = 25 °C		2.6 ^b		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	30		
Avalanche Energy	L = 0.1 IIII	E _{AS}	45	mJ	
	T _C = 25 °C	P _D	48.1	w	
Maximum Power Dissipation	T _C = 70 °C		30.8		
	T _A = 25 °C		3.1 ^b		
	T _A = 70 °C		2.0 ^b		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^b	Steady State	R_{thJA}	32	40	°C/W
Maximum Junction-to-Case	Steady State	R_{thJC}	2.1	2.6	O/VV

Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.

Document Number: 68647 S10-0109-Rev. B, 18-Jan-10

SUD50N04-8m8P

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					L	L	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 10		44		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 1.0 mA		- 5.9			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.5		3.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zava Cata Valtana Duain Commant		V _{DS} = 40 V, V _{GS} = 0 V			1	μА	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V, T _J = 70 °C			20		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Dunin Course On Otata Basistanasi		V _{GS} = 10 V, I _D = 20 A		0.0069	0.0088		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 15 A		0.0084	0.0105	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 15 A		75		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2400		pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		260			
Reverse Transfer Capacitance	C _{rss}			100			
Total Cata Charres	Q _g -	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		37	56	nC	
Total Gate Charge				16	24		
Gate-Source Charge	Q_{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		6.5			
Gate-Drain Charge	Q _{gd}			4.5			
Gate Resistance	R_{g}	f = 1 MHz	2.5	5.5	8.5	Ω	
Turn-On Delay Time	t _{d(on)}			30	45		
Rise Time t _r		$V_{DD} = 20 \text{ V}, R_L = 1 \Omega$		15	25		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		45	70	ns	
Fall Time	t _f			15	25		
Turn-On Delay Time	t _{d(on)}			9	15		
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_L = 1 \Omega$		5	10		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		40	60		
Fall Time	t _f			5	10		
Drain-Source Body Diode Characteris	tics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			40	Α	
Pulse Diode Forward Current ^a	I _{SM}				100	^	
Body Diode Voltage	V_{SD}	I _S = 10 A		0.81	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			22	35	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 20 A dl/dt = 100 A/vs T = 05 °C		14	25	nC	
Reverse Recovery Fall Time t _a		$I_F = 20 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		11			
Reverse Recovery Rise Time	t _b			11		ns	

Notes:

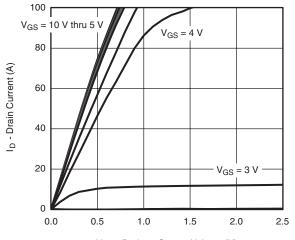
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

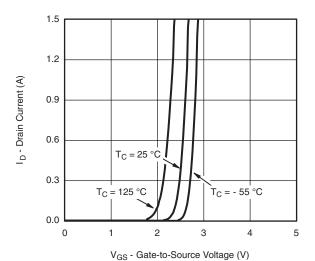


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

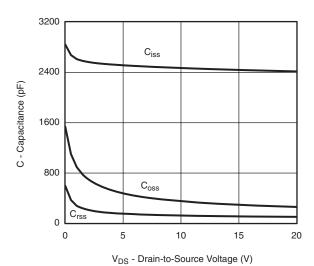


V_{DS} - Drain-to-Source Voltage (V)

Output Characteristics



Transfer Characteristics

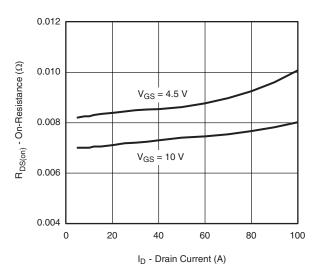


Capacitance

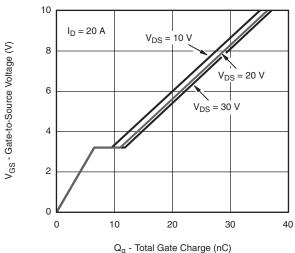
(V) tuguno uiguo 60 T_C = 25 °C T_C = -55 °C T_C = -55 °C

 V_{GS} - Gate-to-Source Voltage (V)

Transfer Characteristics



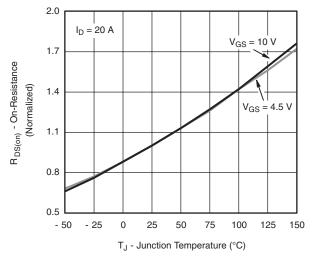
On-Resistance vs. Drain Current



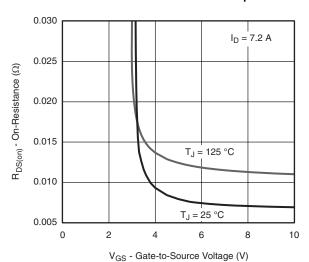
Gate Charge

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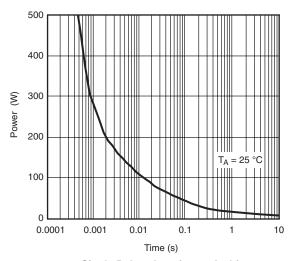
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



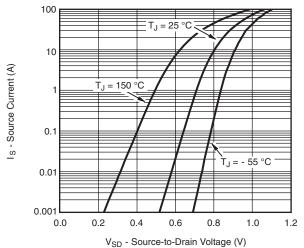
On-Resistance vs. Junction Temperature



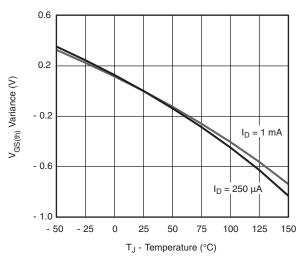
On-Resistance vs. Gate-to-Source Voltage



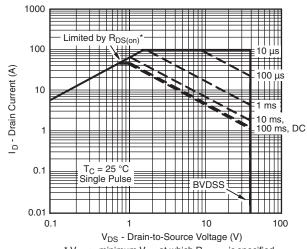
Single Pulse, Junction-to-Ambient



Source-Drain Diode Forward Voltage



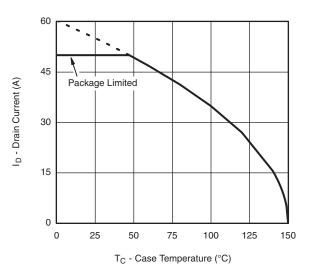
Threshold Voltage



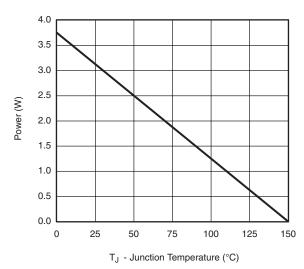
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

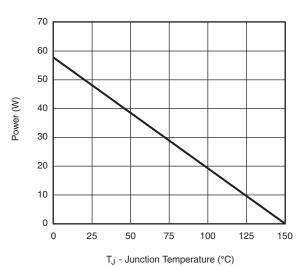


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating*, Junction-to-Case





Power Derating, Junction-to-Ambient

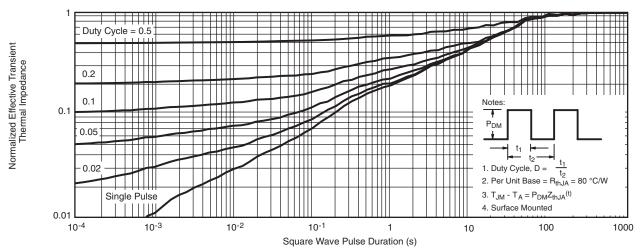
Power Derating, Junction-to-Case

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

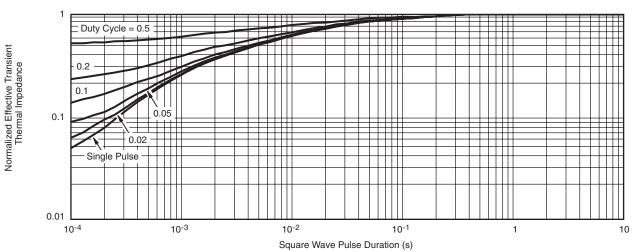
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



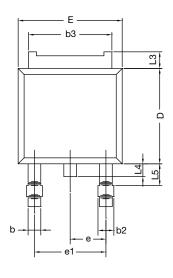
Normalized Thermal Transient Impedance, Junction-to-Case

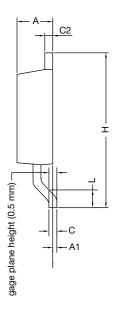
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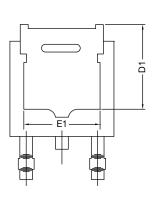


TO-252AA Case Outline

VERSION 1: FACILITY CODE = Y







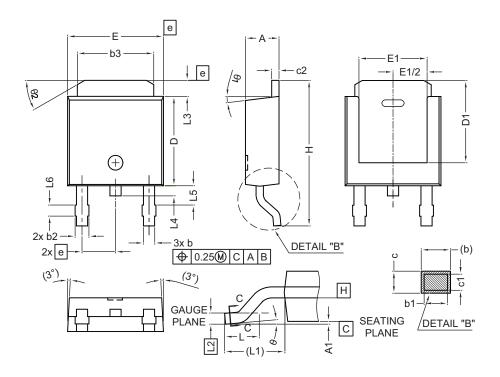
	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
Е	6.35	6.73	
E1	4.32	=	
Н	9.40	10.41	
е	2.28 BSC		
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

Note

• Dimension L3 is for reference only



VERSION 2: FACILITY CODE = N



	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	-	
Е	6.35	6.73	
E1	4.32 -		
е	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022

DWG: 5347



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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